



## Product Change Notification: DSNO-07CTBY708

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**Date:**

21-May-2026

**Product Category:**

Memory

**Notification Subject:**

CCB 8242 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material for 23A256-I/SN, 23A256T-I/SN, 23A640-I/SN, 23A640T-I/SN, 23K256-E/SN, 23K256-I/SN, 23K256T-E/SN, 23K256T-I/SN, 23K640-E/SN, 23K640-I/SN, 23K640T-E/SN and 23K640T-I/SN catalog part numbers (CPN) available in 8L SOIC (3.90mm) package at MTAI assembly site.

**Affected CPNs:**

[DSNO-07CTBY708\\_Affected\\_CPN\\_05212026.pdf](#)

[DSNO-07CTBY708\\_Affected\\_CPN\\_05212026.csv](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material for 23A256-I/SN, 23A256T-I/SN, 23A640-I/SN, 23A640T-I/SN, 23K256-E/SN, 23K256-I/SN, 23K256T-E/SN, 23K256T-I/SN, 23K640-E/SN, 23K640-I/SN, 23K640T-E/SN and 23K640T-I/SN catalog part numbers (CPN) available in 8L SOIC (3.90mm) package at MTAI assembly site.

**Pre and Post Summary Changes:**

	Pre Change	Post Change	Change (Yes/No)

<b>Assembly Site</b>	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No	
<b>Lead-Frame Material</b>	CDA194	CDA194	No	
<b>Wire Material</b>	Au	CuPdAu	Yes	
<b>Die Attach Material</b>	8390A (PFAS-free)	8390A (PFAS-free)	QMI519 (PFAS-free)	Yes
<b>Mold Compound Material</b>	G600V	G600V	No	

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as an additional wire material and QMI519 as a new die attach material.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** September 2026

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

	May 2026					>	September 2026				
Work Week	19	20	21	22	23		36	37	38	39	40
<b>Initial PCN Issue Date</b>			x								
<b>Qual Report Availability</b>										x	
<b>Final PCN Issue Date</b>										x	

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** May 21, 2026: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**[PCN\\_DSNO-07CTBY708\\_Qualification\\_Plan.pdf](#)**

Please contact your local **[Microchip sales office](#)** with questions or concerns regarding this notification.

**Terms and Conditions:**

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